



TECHNOLOGY & COST ANALYST Semiconductor Packaging

System Plus Consulting is a French company specialized in Reverse Costing, performing manufacturing cost analysis from physical analysis of electronics components, strategic consulting to a worldwide customer base. Covering emerging and disruptive silicon and micro manufacturing markets, the group supports companies, and R&D organizations by delivering comprehensive analysis that helps them understand the technology and cost trends critical to their business.

System Plus Consulting is part of Yole Group of companies with offices in France, Germany, Japan, Greater China, Korea and the U.S.A.

JOB DESCRIPTION

As part of our activity's development, we are currently recruiting an experienced **Technology and Cost Analyst specialized in semiconductor packaging** for a position located in our offices in Nantes or Lyon (France) or in Austin (Texas). You will perform technology, cost and strategic analysis on standard or new technologies (3D, SiP, fan-out, flip chip, embedded die...) in end applications (IC, MEMS, Power, RF...) for different markets (consumer, automotive, industrial, medical, defense...)

Within the Semiconductors Devices Department, you will work in close collaboration with the physical analysis laboratory as well as take part in projects with other analysts.

RESPONSABILITES

As an Analyst, you will be responsible to:

- Interacting with the laboratory analysts to do technical analysis of selected devices
- Understanding and describing manufacturing processes thanks to structural and physical analyses made by our internal laboratory
- Understanding the impact of the manufacturing process flow to calculate cost of production
- Understanding and updating technical information on manufacturing processes and cost through survey, interviews and publication research.
- Execute projects within a given timeframe

You will also contribute to the development of the Advanced Packaging activity by:

- Overseeing technology and industry insights from manufacturing trends, components and modules
- Maintaining and enriching internal databases (manufacturing processes and materials, substrates, equipment costs ...)
- Participating in dedicated trade shows and conferences worldwide.

EDUCATION / EXPERIENCE

- University Degree (Master, Engineer, PhD) in a semiconductor and possibly advanced packaging field
- Experience (3-5 years) in semiconductor packaging technologies: 3D, System In Package, flip chip, fan out, wafer level-packaging as well as advanced substrate
- Deep interest in economics and cost related subjects
- Communication and presentation skills
- Team player and organizational skills
- Excellent English speaking / writing is mandatory. Proficiency in French is a plus

Please send your latest CV & cover letter to recruiting@systemplus.fr

